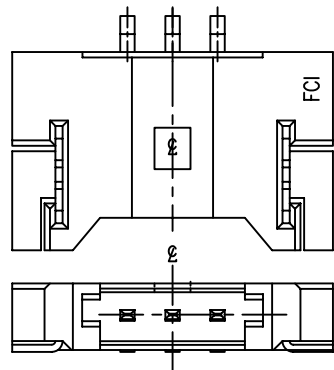
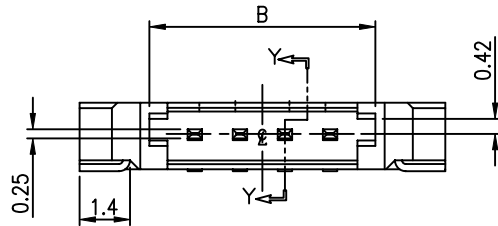
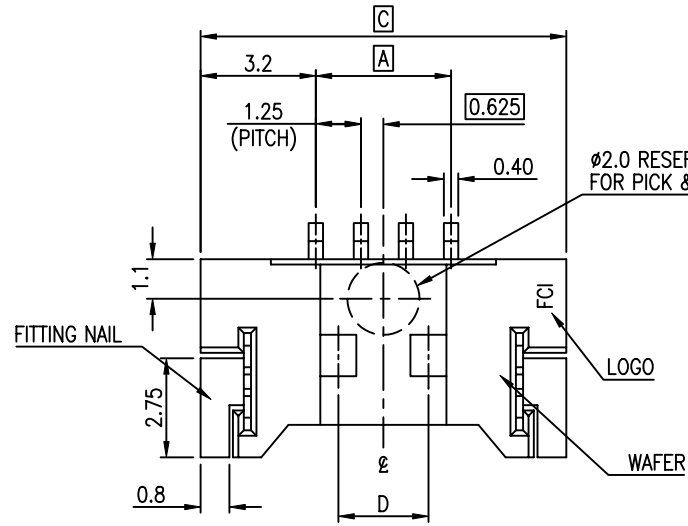
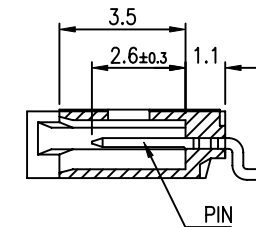
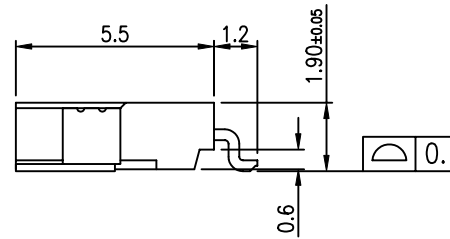
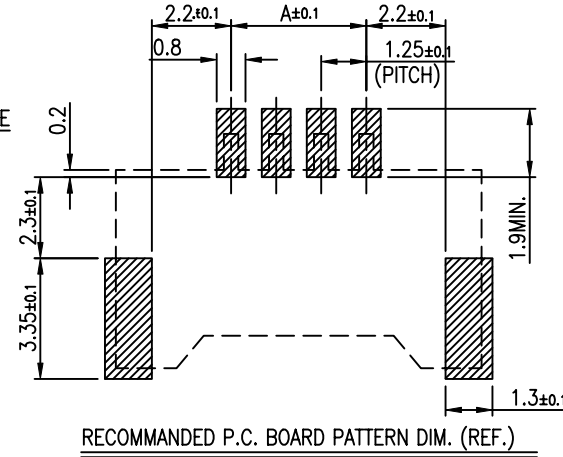




FOR 2 & 3 PIN



SECT. Y-Y

- NOTES:
- MATERIAL:
 - 1.1 HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 - FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: GOLD FLASH 1u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - GOLD FLASH 1u" MIN. OVERALL
 - REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 - SPEC. PLS. REFER TO GS-12-573.
 - PACKAGE PLS. REFER TO GS-14-1315.
 - PART NUMBER DESCRIPTION:
 - 10089716-XXX 0 0 0 LF
 - LEAD FREE
 - COLOR
 - 0: NATURAL
 - PLATING
 - 0: GOLD FLASH
- NO. OF CONTACTS
- PACKING
- 0: TAPE & REEL

CKT	Dim.A	Dim.B	Dim.C	Dim.D
002	1.25	3.77	7.65	--
003	2.50	5.02	8.90	--
004	3.75	6.27	10.15	2.50
005	5.00	7.52	11.40	3.75
006	6.25	8.77	12.65	5.00
009	10.00	12.52	16.40	8.75

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI	
ltr	ecn no	dr	date	linear	.X ± 0.25	projection	title	www.fciconnect.com	
A	T08-1164	WL	08/11/08	linear	.XX ± 0.15	MM	1.25mm WIRE TO BOARD		
B	T08-1185	WL	11/13/08	linear	.XXX ± 0.10	MM	WAFER SMT R/A TYPE		
C	T08-1196	WL	12/10/08	angles	0° ± 2°	MM	product family	WTB	code
D	T09-1001	WL	01/05/09	dr	LEIF SHEN	06/18/08	size	dwg no	TWN
E	T09-1005	WL	01/20/09	enr	LEIF SHEN	06/18/08	A4		10089716
F	T09-1077	WL	06/05/09	chr	LEIF SHEN	06/18/08			
				appd	JOSEPH HSIA	06/18/08			sheet
sheet index	revision	F	1						1 of 1